PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Min-Feng Kao	07/13/2011
Dun-Nian Yaung	07/13/2011
Jen-Cheng Liu	07/13/2011
Chun-Chieh Chuang	07/13/2011
Wen-De Wang	07/13/2011

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	13185204	

CORRESPONDENCE DATA

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Dallas, TEXAS 75219 Address Line 4:

ATTORNEY DOCKET NUMBER:	24061.1811 - ERIC LI
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NAME OF SUBMITTER: Eric Q. Li

Total Attachments: 3

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> **PATENT** REEL: 026608 FRAME: 0633

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Docket No.: 2011-0279 / 24061.1811

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1)	Min-Feng Kao	of	No. 15, Lane 224, Wufeng S. Road, East District Chiayi City 600, Taiwan, R.O.C.
(2)	Dun-Nian Yaung	of	4F, No. 15, Lane 130, Wansheng Street, Wunshan District Taipei City 116, Taiwan, R.O.C.
(3)	Jen-Cheng Liu	of	5F, #219 Guan-Dong Road Minsyong Township, Chiayi County 621, Taiwan, R.O.C.
(4)	Chun-Chieh Chuang	of	No. 61, Meinan Street Tainan City, Taiwan, R.O.C.
(5)	Wen-De Wang	of	No. 17, Jhonghe Village Minsyong Township, Chiayi County 621, Taiwan, R.O.C.

have invented certain improvements in

NOVEL CMOS IMAGE SENSOR STRUCTURE

for which we have executed an application for Letters Patent of the United States of America on July 18, 2011, as U.S. Serial No. 13/185, 204; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

-1-

Docket No.: 2011-0279 / 24061.1811

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Min-Feng Kao	
Residence Address:	No. 15, Lane 224, Wufeng S. I Chiayi City 600, Taiwan, R.O.	
Dated: 2/13 / 2	2011	Min-Leng Kao Inventor Signature
Inventor Name:	Dun-Nian Yaung	
Residence Address:	4F, No. 15, Lane 130, Wanshe Taipei City 116, Taiwan, R.O.	•
Dated: 7/3	15011	Inventor Signature
Inventor Name:	Jen-Cheng Liu	
Residence Address:	5F, #219 Guan-Dong Road Minsyong Township, Chiayi County 621, Taiwan, R.O.C.	
Dated: 7/L	(3/20//	Jen-Cheny Lily Inventor Signature

Docket No.: 2011-0279 / 24061.1811

Customer No.: 42717

Inventor Name:

Chun-Chieh Chuang

Residence Address:

No. 61, Meinan Street

Tainan City, Taiwan, R.O.C.

Inventor Signature

Churchiek Chuange

Inventor Name:

Wen-De Wang

Residence Address:

No. 17, Jhonghe Village

Minsyong Township, Chiayi County 621, Taiwan, R.O.C.

- 3 -

Inventor Signature

RECORDED: 07/18/2011